

背面减薄砂轮

Back Grinding Wheels

Back grinding wheels are mainly used for the thinning and grinding of the semiconductor wafers. Matched Grinding Machine: Japanese, German, American, Korean and Chinese grinders. Good TTV and less damage section.

减薄砂轮主要应用于半导体晶圆的减薄与精研加工。我公司生产的减薄砂轮可配在日本、德国、美国、韩国及国产磨床上稳定使用。

Workpiece : discrete devices, integrated chips(IC) and virgin silicon wafer of etc.

Material of workpiece: Silicon, GaAs , InP , SiC and some other semiconductor materials.

Applications: back thinning, rough grinding and fine grinding.

加工对象：分立器件、集成电路衬底及原始晶片等。

工件材料：单晶硅、砷化镓、磷化铟、碳化硅等半导体材料。

应用工序：背面减薄、正面磨削的粗磨加工和精研加工。

Main features:

Easy grinding with low and consistent current

No edge chipping and less damage

Long wheel life

主要特点:

电流低且稳定

无崩边，损伤层小

寿命长

形状代号 Shape code	剖面简图 Profile sketch	常用规格 Conventional specification		
		外径 D	厚度 T	孔径 H
6A2 or 6A2H		175	30、35	76
		200	35	76
		350	45	127
6A2T		195	22.5、25	170
		280	30	228.6
		313	30	237
6A2T (三椭圆形) ircular		350	35	235
		209	22.5	158
T、E、W、X 可根据客户要求加工				
T,E,W,X according to the customer's requirements				